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*Substitute Specification*

Application No. 09/337,040

MULTIPLE EXPOSURE METHOD

FIELD OF THE INVENTION AND RELATED ART

[0001] This invention relates to an exposure method and an exposure apparatus and, more particularly, to an exposure method and an exposure apparatus for lithographically printing a fine circuit pattern on a photosensitive substrate. The exposure method or exposure apparatus of the present invention is usable for the manufacture of various devices such as semiconductor chips (ICs or LSIs), display devices (liquid crystal panels), detecting devices (magnetic heads), or image pickup devices (CCDs), for example.

[0002] Generally, the manufacture of devices such as ICs, LSIs or liquid crystal panels based on lithography uses a projection exposure method and a projection exposure apparatus by which a circuit pattern of a photomask or reticle (hereinafter, "mask") is projected through a projection optical system onto a photosensitive substrate such as a silicon wafer or glass plate (hereinafter, "wafer") having a photoresist coating applied thereto, whereby the pattern is printed on the substrate.

[0003] Enlargement in the density of such a device has forced a reduction in the linewidth of a pattern to be printed on a wafer as well as an increase in area of a chip to be produced on the wafer. In the field of projection exposure methods and projection exposure apparatuses, most important in wafer micro-processing technology, improvements in resolution and

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